

Amendments to the Specification

Please replace paragraph [0108] at page 17, lines 21-24 of the specification, with the paragraph provided below:

[0108] In this case, the semiconductor chip 10 is face-down-bonded to the substrate 70. The semiconductor chip 10 and the substrate 70 are bonded to each other with an ~~anisotropically conductive~~ material 74. The bumps 40 and the wiring pattern 72 are electrically connected with conductive particles.